

Amendments to the Abstract are as follows:

ABSTRACT OF THE DISCLOSURE

A circuit device includes a substrate, a semiconductor chip mounted on the substrate, and a sealing layer for sealing the semiconductor chip to cover the semiconductor chip. The sealing layer includes a silicone-based material that has a thixotropic index from 2 to 6 and an elastic coefficient of 1 to 50 MPa. A shielding member is attached to the substrate and covers the sealing layer.